



## Material Content Data Sheet



<b>Sales Product Name</b>				TDA21220		<b>Issued</b>		24. January 2018	
<b>MA#</b>				MA001159680					
<b>Package</b>				PG-IQFN-40-1		<b>Weight*</b>		100.11 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.536	1.53	1.53	15343	15343	
leadframe	inorganic material	phosphorus	7723-14-0	0.013	0.01		127		
	non noble metal	zinc	7440-66-6	0.051	0.05		510		
	non noble metal	iron	7439-89-6	1.020	1.02		10191		
wire	non noble metal	copper	7440-50-8	41.428	41.37	42.45	413809	424637	
	noble metal	gold	7440-57-5	0.308	0.31	0.31	3073	3073	
encapsulation	organic material	carbon black	1333-86-4	0.086	0.09		856		
	plastics	epoxy resin	-	4.415	4.41		44100		
	inorganic material	silicondioxide	60676-86-0	38.363	38.32	42.82	383203	428159	
leadfinish	non noble metal	tin	7440-31-5	1.567	1.57	1.57	15657	15657	
plating	noble metal	silver	7440-22-4	1.920	1.92	1.92	19181	19181	
glue	plastics	epoxy resin	-	0.093	0.09		931		
	noble metal	silver	7440-22-4	0.280	0.28	0.37	2792	3723	
solder	noble metal	silver	7440-22-4	0.036	0.04		355		
	non noble metal	tin	7440-31-5	0.028	0.03		284		
	non noble metal	lead	7439-92-1	1.357	1.36	1.43	13555	14194	
CLIP plating	noble metal	silver	7440-22-4	0.787	0.79	0.79	7860	7860	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002	0.00		20		
	non noble metal	zinc	7440-66-6	0.008	0.01		82		
	non noble metal	iron	7439-89-6	0.164	0.16		1636		
	non noble metal	copper	7440-50-8	6.651	6.64	6.81	66435	68173	
*deviation	< 10%			Sum in total:		100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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